Sryeo Electronic Paste Co., Ltd.
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Product Specification

Product:	Copper Paste For Filling Holes
Part Number:	01L-5905

Application Scope :

Single-component conductor paste series, a low-temperature copper paste for filling holes, is dense and exhibits excellent conductivity. It provides superior electrical performance with good printability and oxidation resistance. The conductivity remains stable without significant deviation during post-printing processing or bending during product use, suitable for screen printing.

Usage Conditions :

Substrate	Ceramic substrate, resin plate
Usage Method	200-250 mesh screen printing
Leveling	Level at room temperature for 3-5 minutes (time adjusted according to actual leveling conditions)
Solidify	In an incubator at a constant temperature of 80-150°C for 10-30 minutes (For reference only. The actual baking temperature and time can be adjusted as needed.)
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤15μm	FOG test
2	Viscosity	200-420Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10 rpm, with viscosity adjustable to 25±1°C according to user requirements.
3	Solid Content	70%	Copper，Glue

2. Characteristics After Curing :

Under the condition of 1 sintering,Check fired film produced under the conditions specified in 1）

Characteristics		Standard	Test Method And Conditions
4	Resistivity	≤150mΩ/□	The cured film thickness is 8-20μm, and the test pattern size is 100mm*1mm.
5	Hardness	2H	Pencil hardness
6	Adhesion	Not fall off	3M 600#Tape 90°Pull

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of six months from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.